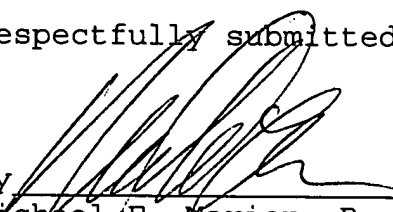


reserve their right to reintroduce subject matter deleted herein at a later time during the prosecution of this application or continuing applications.

Respectfully submitted,

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## APPENDIX

3. (amended) A detector as claimed in ~~the claims 1 and 2~~claim 1, characterized in that the adhesive (A) is a fast curing epoxy resin, cyanoacrylate or acrylate adhesive.

11. (amended) A method of forming a detector for the detection of electromagnetic radiation which detector includes at least one scintillator (6), at least one CMOS chip (3) and one ceramic basic element (4), wherein a respective intermediate layer (2) that is defined in respect of its gap width is arranged each time between the scintillator (6) and the CMOS chip (3) and between the CMOS chip (3) and the ceramic basic element (4), and wherein said intermediate layer (2) contains at least two adhesives (A, B) of different consistency and spacers (5), and ~~as claimed in claim 1,~~ where first an intermediate layer (2) is formed between a CMOS chip (3) and a ceramic basic element (4), where spacers (5) and quantities of an adhesive (A1) are applied to a surface of the ceramic basic element (4) during the first step, where the applied quantities of an adhesive (A1) project from the spacers (5), where subsequently the CMOS chip (3) is placed on said quantities and is bonded and fixed while resting on the spacers (5) and quantities of the adhesive (A1), and where during a second step the gap remaining

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between the CMOS chip (3) and the ceramic basic element (4) is  
completely filled with an adhesive (B) which is applied to a side  
of the CMOS chip (3) in the horizontal position and enters the gap  
under the influence of capillary forces and is subsequently allowed  
to cure ~~in conformity with claim 9~~ and subsequently an a second  
intermediate layer (2) is formed between a scintillator (6) and a  
CMOS chip (3), where at least quantities of the adhesive (A2) are  
applied, during the first step, to the bumps that are provided in  
optically inactive regions of the CMOS chip surface, after which  
the scintillator (6) is arranged on the bumps and is bonded and  
fixed while resting on the bumps and on the quantities of an  
adhesive (A2), and where in a second step the gap remaining between  
the scintillator (6) and the CMOS chip (3) is completely filled  
with an adhesive (B) which is applied to one side of the  
scintillator (6) in the horizontal position and enters the gap  
under the influence of capillary forces and is subsequently allowed  
to cure ~~in conformity with claim 10.~~

12. (amended) An X-ray examination apparatus that includes at  
least one detector as claimed in ~~one of the claims 1 to 8~~ claim 1.